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•	State-of-the-Art Advanced BiCMOS
	Technology (ABT) Design for 3.3-V
	Operation and Low-Static Power
	Dissipation

- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Bus-Hold Data Inputs Eliminate the Need for External Pullup Resistors
- Support Live Insertion
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Ceramic (J) DIPs

SN74LVT240 DB, DW, OR PW PACKAGE (TOP VIEW)										
10E [1 1A1 [2 2Y4 [3 1A2 [4 2Y3 [5 1A3 [6 2Y2 [7 1A4 [8 2Y1 [9 GND [1	3 18 4 17 5 16 5 15 7 14 3 13	V _{CC} 2OE 1Y1 2A4 1Y2 2A3 1Y3 2A2 1Y4 2A1								

SN54LVT240 ... J PACKAGE

SN54LVT240 . . . FK PACKAGE (TOP VIEW)

	2Y4 1A1 V _{CC} 2 <u>0E</u>	
1A2 2Y3 1A3 2Y2 1A4	$\begin{bmatrix} 3 & 2 & 1 & 20 & 19 \\ 4 & & & 18 \end{bmatrix}$	1Y1
2Y3	5 17	2A4
1A3	$\begin{bmatrix} 4 & & & & & \\ 18 & & & & & \\ 15 & & & & & 17 \\ 6 & & & & & 16 \end{bmatrix}$	1Y2
2Y2	[7 15]	2A3 1Y3
1A4	8	1Y3
	9 10 11 12 13	
	2Y1 GND 2A1 1Y4 2A2	
	$\sim - \sim \sim$	

description

These octal buffers and line drivers are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

These devices are organized as two 4-bit buffer/line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the devices pass data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVT240 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54LVT240 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74LVT240 is characterized for operation from -40° C to 85° C.



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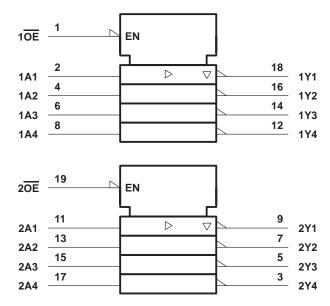


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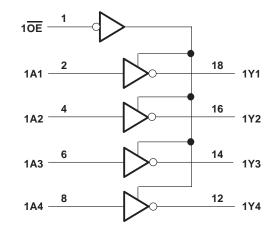
FUNCTION TABLE (each buffer)											
INP	INPUTS OUTPUT										
OE	Α	Y									
L	Н	L									
L	L	н									
Н	Х	Z									

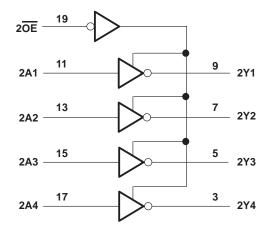
logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)







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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	
Voltage range applied to any output in the high state or power-off state, V_{Ω} (see Note 1)0.5 V to	
Current into any output in the low state, I _O : SN54LVT240	mΑ
SN74LVT240 128	mΑ
Current into any output in the high state, I _O (see Note 2): SN54LVT240	mΑ
SN74LVT240 64	mΑ
Input clamp current, I _{IK} (V _I < 0)	mΑ
Output clamp current, I_{OK} ($V_O < 0$)	mΑ
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 3): DB package	3 W
DW package 1.6	3 W
PW package	
Storage temperature range, T _{stg} –65°C to 150	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. This current flows only when the output is in the high state and $V_O > V_{CC}$.

3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology Data Book, literature number SCBD002B.

recommended operating conditions (see Note 4)

			SN54L	VT240	SN74L	UNIT	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	2.7	3.6	2.7	3.6	V	
VIH	High-level input voltage		2	EW	2		V
VIL	Low-level input voltage					0.8	V
VI	Input voltage			č 5.5		5.5	V
IOH	High-level output current		Ç,	-24		-32	mA
IOL	Low-level output current		na l	48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled	24	10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.



SN54LVT240, SN74LVT240 3.3-V ABT OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS SCBS134F - SEPTEMBER 1992 - REVISED JULY 1995

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS			SN	54LVT2	40	SN				
PARAMETER		FEST CONDITIONS		MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNIT	
VIK	V _{CC} = 2.7 V,	lj = -18 mA				-1.2			-1.2	V	
	$V_{CC} = MIN \text{ to } MAX^{\ddagger}$, I _{OH} = -100 μA	V _{CC} -0).2		V _{CC} -0	.2				
Vou	V _{CC} = 2.7 V,	I _{OH} = - 8 mA		2.4			2.4			V	
VOH	V _{CC} = 3 V	I _{OH} = - 24 mA		2						v	
	vCC = 2 v	$I_{OH} = -32 \text{ mA}$					2				
	V _{CC} = 2.7 V	I _{OL} = 100 μA				0.2			0.2		
	$v_{\rm CC} = 2.7 v$	I _{OL} = 24 mA				0.5			0.5		
VOL		I _{OL} = 16 mA				0.4			0.4	v	
VOL	$V_{CC} = 3 V$	I _{OL} = 32 mA				0.5			0.5	v	
	VCC = 3 V	I _{OL} = 48 mA	0.55								
		I _{OL} = 64 mA				IE)			0.55		
	$V_{CC} = 0 \text{ or MAX}^{\ddagger},$	VI = 5.5 V		22	10			10			
łı	V _{CC} = 3.6 V	$V_I = V_{CC}$ or GND	Control inputs		2	±1			±1		
Ч		$V_I = V_{CC}$	Data inputs		5	1			1	μΛ	
		$V_{I} = 0$	Data inputs		2	-5			-5	μΑ μΑ	
loff	$V_{CC} = 0,$	V_{I} or $V_{O} = 0$ to 4.5 V	V	20	7				±100	μA	
l(hold)	$V_{CC} = 3 V$	VI = 0.8 V	Data inputs	75			75			лΔ	
'I(noid)		V _I = 2 V	Buta inputo	-75			-75			μπ	
IOZH	V _{CC} = 3.6 V,	V _O = 3 V				5			5	μA	
IOZL	V _{CC} = 3.6 V,	$V_{O} = 0.5 V$				-5			-5	μΑ	
			Outputs high		0.12	0.19		0.12	0.19		
ICC	$V_{\rm CC} = 3.6 \text{ V}, \qquad I_{\rm O} = 0,$	l _O = 0,	Outputs low		8.6	12		8.6	12	2 mA	
	$V_I = V_{CC}$ or GND		Outputs disabled		0.12	0.19		0.12	0.19		
∆ICC§	$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$ One input at $V_{CC} - 0.6 \text{ V},$ Other inputs at V_{CC} or GND					0.2			0.2	mA	
Ci	V _I = 3 V or 0	3 V or 0						4		pF	
Co	$V_{O} = 3 V \text{ or } 0$				8			8		pF	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$. [‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



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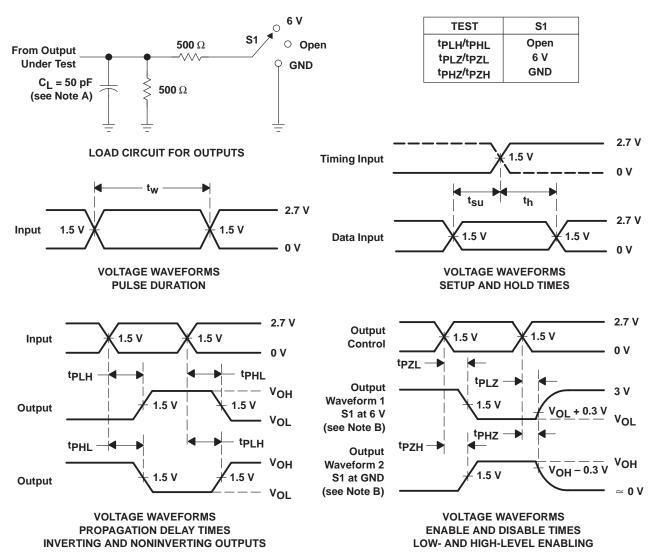
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

				SN54L	VT240			SN	74LVT2	40		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V				7 V V _{CC} = 3.3 V ± 0.3 V		V	V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN	MAX	
^t PLH	А	v	1	4.2	N.	5.2	1	2.9	4.1		5.2	ns
^t PHL	A	1	1.3	3.7	R	4.1	1.3	2.5	3.5		4	115
^t PZH	OE	v	1.2	4.7	1	5.7	1.2	3.2	4.6		5.6	ns
^t PZL	ÛE	I	1.5	4.8		5.9	1.4	3.5	4.7		5.8	115
^t PHZ	ŌĒ	v	2	5.3		5.7	2	3.6	5.2		5.5	ns
^t PLZ		1	1.9	Q 4.6		4.6	1.9	3.2	4.4		4.4	115

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_Q = 50 Ω, t_f ≤ 2.5 ns. t_f ≤ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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